



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2812
#12/C
w/attach
4-10-03
Mullish

In re application of : Confirmation No. 3064
Hiroaki INOUE et al. : Docket No. 2001_1094A
Serial No. 09/890,455 : Group Art Unit 2812
Filed March 12, 2002 : Examiner Lynne A. Gurley

ELECTROLESS PLATING LIQUID AND METHOD
OF FORMING INTERCONNECTION USING SUCH
AN ELECTROLESS PLATING LIQUID

AMENDMENT

Assistant Commissioner for Patents,
Washington, D.C.

Sir:

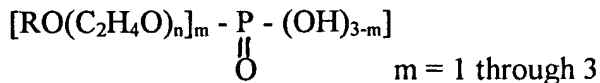
Responsive to the Official Action dated December 31, 2002, please amend the above-identified application as follows:

IN THE SPECIFICATION

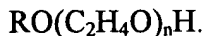
Page 5, lines 19-25, please replace the paragraph with the following rewritten paragraph:

The electroless copper plating liquid should preferably further contain polyoxyethylene alkylether phosphoric acid, polyoxyethylene alkylether, and a mixture of polyoxyethylene alkylether phosphoric acid and polyoxyethylene alkylether (e.g., RT610 manufactured by Toho Chemical Industry Co., Ltd.), indicated below, at a concentration ranging from 1 to 100 mg/L

(polyoxyethylene alkylether phosphoric acid)



(polyoxyethylene alkylether)



RECEIVED
MAR - 2 2003
TECHNOLOGY CENTER 2800